

In-line module cleaning

Since March 2003, the Zestron® division of Dr. O.K. Wack Chemie GmbH based in Ingolstadt has been performing cleaning trials using a horizontal conveyorized cleaning line supplied by Pill e.K., Auenwald.



The in-line spray cleaning technique is of particular interest to this producer, which is keen to avoid labour-intensive handling processes between the soldering and cleaning stage due to its high production throughput. Both for cleaning FR4 modules and also DCB ceramic substrates, the technique has proven highly successful over wide-ranging field trials. This type of spray cleaning method has become established in the USA, particularly in conjunction with water-based cleaning agents, and is now meeting with growing enthusiasm also by European users.

Particular benefits of the system:

- No manual part handling -> fully automated system for high throughput rates
- Short contact times with cleaning agents, resulting in excellent material compatibility for an extremely wide part spectrum

Used in conjunction with water-based MPC cleaning agents, the process permits major cost savings compared to solvent-based versions: Not only can costly rinsing stages can be omitted, the expense involved in rinsing water treatment is also substantially reduced.